

4:1 High-Speed USB Multiplexer/Switch

1 FEATURES

- **Wide Bandwidth: 550MHz**
- **Supply Operation +2.5V to +4.4V**
- **Low ON Resistance, 6Ω (TYP) at 3.3V**
- **1.8V Logic Threshold Compatibility for Control Inputs**
- **Rail-to-Rail Operation**
- **Fast Switching Time**
- **Operating Temperature Range: -40°C to 125°C**
- **Packages: UQFN2.6X1.8-16**

2 APPLICATIONS

- **Routes Signals for USB 1.0, 1.1, and 2.0**
- **MP3 and Other Personal Media Players**
- **Mobile POS and Portable POS**
- **USB Switching for TV Display Panel**

3 DESCRIPTIONS

The RS2274 is a bi-directional, low-power, high-speed USB 2.0 switch comprised of dual 4:1 multiplexers. RS2274 has very low on-resistance, allowing the inputs to be connected to the outputs without adding propagation delay. It is optimized for switching from four high-speed (480Mbps) sources or any combination of high-speed and full-/low-speed USB/UART sources to one USB 2.0 connector.

The RS2274 is available in Green UQFN2.6X1.8-16 packages. It operates over an ambient temperature range of -40°C to 125°C.

Device Information ⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|----------------|-----------------|
| RS2274 | UQFN2.6X1.8-16 | 2.60mm×1.80mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Table of Contents

| | |
|--|-----------|
| 1 FEATURES | 1 |
| 2 APPLICATIONS | 1 |
| 3 DESCRIPTIONS | 1 |
| 4 REVISION HISTORY | 3 |
| 5 PACKAGE/ORDERING INFORMATION ⁽¹⁾ | 4 |
| 6 LOGIC FUNCTION | 5 |
| 7 PIN CONFIGURATIONS | 6 |
| 8 SPECIFICATIONS..... | 7 |
| 8.1 Absolute Maximum Ratings | 7 |
| 8.2 ESD Ratings | 7 |
| 8.3 Recommended Operating Conditions | 7 |
| 8.4 DC Electrical Characteristics..... | 8 |
| 8.5 AC Electrical Characteristics | 9 |
| 9 PARAMETER MEASUREMENT INFORMATION | 10 |
| 10 APPLICATION AND IMPLEMENTATION | 12 |
| 11 PACKAGE OUTLINE DIMENSIONS | 13 |
| 12 TAPE AND REEL INFORMATION | 14 |

4 REVISION HISTORY

Note: Page numbers for previous revisions may different from page numbers in the current version.

| VERSION | Change Date | Change Item |
|---------|-------------|--|
| A.0 | 2024/05/17 | Preliminary version completed |
| A.0.1 | 2024/05/20 | 1. Modify FEATURES, APPLICATIONS and DESCRIPTIONS 2. Modify PIN DESCRIPTION 3. Add UQFN2.6X1.8-16 Land Pattern |
| A.1 | 2025/01/06 | Initial version completed |
| A.2 | 2025/02/11 | Delete QFN3X3-16 Package |
| A.3 | 2025/09/10 | Add 10 APPLICATION AND IMPLEMENTATION |

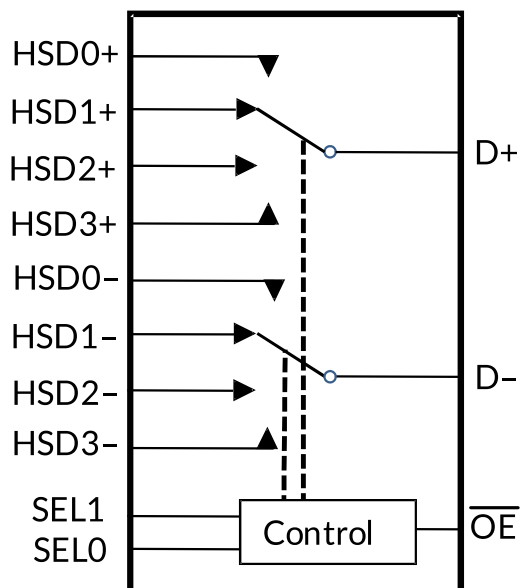
5 PACKAGE/ORDERING INFORMATION ⁽¹⁾

| PRODUCT | ORDERING NUMBER | TEMPERATURE RANGE | PACKAGE LEAD | PACKAGE MARKING ⁽²⁾ | MSL ⁽³⁾ | PACKAGE OPTION |
|---------|-----------------|-------------------|----------------|--------------------------------|--------------------|---------------------|
| RS2274 | RS2274XTQQ16 | -40°C ~125°C | UQFN2.6X1.8-16 | 2274 | MSL3 | Tape and Reel, 3000 |

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) Runic classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F. Please align with Runic if your end application is quite critical to the preconditioning setting or if you have special requirement.

6 LOGIC FUNCTION



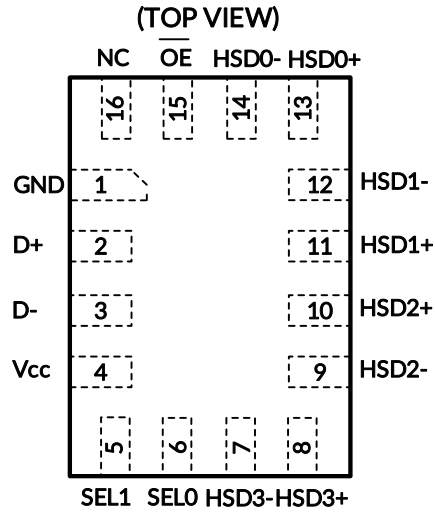
FUNCTION TABLE

| \overline{OE} | SEL0 | SEL1 | Function |
|-----------------|------|------|--------------------------|
| 1 | X | X | D+, D- Switch paths open |
| 0 | 0 | 0 | D+ = HSD0+, D- = HSD0- |
| 0 | 1 | 0 | D+ = HSD1+, D- = HSD1- |
| 0 | 0 | 1 | D+ = HSD2+, D- = HSD2- |
| 0 | 1 | 1 | D+ = HSD3+, D- = HSD3- |

X=Don't care

NOTE: Input and output pins are identical and inter-changeable. Either may be considered an input or output; signals pass equally well in either direction.

7 PIN CONFIGURATIONS



UQFN2.6X1.8-16

PIN DESCRIPTION

| NAME | PIN | FUNCTION |
|-----------------|----------------|---|
| | UQFN2.6X1.8-16 | |
| D+ | 2 | D+ common port |
| D- | 3 | D- common port |
| HSD0+ | 13 | D+ from first source path |
| HSD0- | 14 | D- from first source path |
| HSD1+ | 11 | D+ from second source path |
| HSD1- | 12 | D- from second source path |
| HSD2+ | 10 | D+ from third source path |
| HSD2- | 9 | D- from third source path |
| HSD3+ | 8 | D+ from fourth source path |
| HSD3- | 7 | D- from fourth source path |
| GND | 1 | Ground |
| V _{CC} | 4 | Power Supply |
| \overline{OE} | 15 | Enable control pin, Pull Low enable this device |
| SEL1 | 5 | Digital Control Pin |
| SEL0 | 6 | Digital Control Pin |
| NC | 16 | No connect |

NOTE:

1. This analog switch is no direction, each port can as input or output.

8 SPECIFICATIONS

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

| SYMBOL | PARAMETER | | MIN | MAX | UNIT |
|--------------------|--|----------------|------|-----------------|------|
| V _{CC} | Supply Voltage | | -0.5 | 5.25 | V |
| V _{CNTRL} | DC Input Voltage (SEL1, SEL0, \overline{OE} , SELS) ⁽²⁾ | | -0.5 | V _{CC} | V |
| V _{SW} | DC Switch I/O Voltage ⁽¹⁾ | | -0.5 | 5.25 | V |
| I _{IK} | DC Input Diode Current | | -30 | | mA |
| θ _{JA} | Package thermal impedance ⁽³⁾ | UQFN2.6X1.8-16 | | 145 | °C/W |
| T _{STG} | Storage Temperature | | -65 | 150 | °C |

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) All unused digital inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

(3) The package thermal impedance is calculated in accordance with JESD-51.

8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

| SYMBOL | PARAMETER | VALUE | UNIT |
|--------|---|----------------|-------|
| ESD | IEC61000-4-2 System on USB connector pins D+ & D- | Contact | ±8 |
| | Human Body Model, JEDEC: JESD22-A114 | D+, D- to GND | ±7 |
| | | Power to GND | ±7 |
| | | All Other Pins | ±4 |
| | Charged-Device Model (CDM), ANSI/ESDA/JEDEC JS-002-2018 | | ±1000 |
| | Machine Model (MM), JESD22-A115C (2010) | | ±200 |



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

| SYMBOL | PARAMETER | MIN | MAX | UNIT |
|--------------------|--|------|-----------------|------|
| V _{CC} | Supply Voltage | 2.5 | 4.4 | V |
| V _{CNTRL} | Control Input Voltage (SEL1, SEL0, \overline{OE} and SELS) | 0 | V _{CC} | V |
| V _{SW} | Switch I/O Voltage | -0.5 | 4.4 | V |
| T _A | Operating Temperature | -40 | 125 | °C |

8.4 DC Electrical Characteristics

All typical values are for $V_{CC}=3.3V$ at $25^{\circ}C$ unless otherwise specified, FULL = $-40^{\circ}C - 125^{\circ}C$.

| PARAMETER | SYMBOL | CONDITIONS | V_{CC} (V) | T_A | MIN ⁽²⁾ | TYP ⁽³⁾ | MAX ⁽²⁾ | UNIT |
|---|-----------------|--|--------------|-------|--------------------|--------------------|--------------------|----------|
| On-Resistance | $R_{ON}^{(1)}$ | $V_{SW} = 0.4V$, $I_{ON} = 8mA$, Figure 1 | 3.3 | 25°C | | 6 | 7 | Ω |
| | | | | FULL | | | 9 | |
| On-Resistance Match Between Channels | ΔR_{ON} | $V_{SW} = 0.4V$, $I_{ON} = 8mA$ | 3.3 | 25°C | | 0.34 | 0.5 | Ω |
| | | | | FULL | | | 0.6 | |
| Control Input Leakage | I_{IN} | All Combinations of \overline{OE} SEL1 & SEL0 in the Truth Table ($1=V_{CC}$, $0=0V$) | 4.4 | FULL | -1 | | 1 | μA |
| Off State Leakage | I_{OZ} | $0 \leq D_n$, HSD0n, HSD1n, HSD2n, HSD3n $\leq 4.4V$ | 4.4 | FULL | -1 | | 1 | μA |
| Power-Off Leakage Current (All I/O Ports) | I_{OFF} | $V_{SW} = 0V$ to $4.4V$, Figure 2 | 0 | FULL | -1 | | 1 | μA |
| Sleep Mode Supply Current | I_{CCSLP} | $\overline{OE}=V_{CC}$ | 4.4 | FULL | | | 1 | μA |
| Active Mode Supply Current | I_{CCACT} | All Active Modes in Truth Table | 4.4 | FULL | | 8 | 16 | μA |
| Increase in I_{CC} Current per Control Input and V_{CC} | I_{CCT} | $V_{CNTRL} = 1.8V$ | 4.4 | FULL | | | 3.5 | μA |
| | | $V_{CNTRL} = 1.2V$ | 4.4 | FULL | | | 4 | μA |
| Clamp Diode Voltage | V_{IK} | $I_{IN} = -18mA$ | 2.5 | FULL | | | -1.2 | V |
| Control Input Voltage High | V_{IH} | SEL1, SEL0, \overline{OE} | 2.5 to 4.4 | FULL | 1 | | | V |
| Control Input Voltage Low | V_{IL} | SEL1, SEL0, \overline{OE} | 2.5 to 4.4 | FULL | | | 0.35 | V |

(1) Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).

(2) Limits are 100% production tested at $25^{\circ}C$. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

8.5 AC Electrical Characteristics

All typical values are for $V_{CC}=3.3V$ at $25^{\circ}C$ unless otherwise specified, FULL = $-40^{\circ}C - 125^{\circ}C$.

| PARAMETER | SYMBOL | CONDITIONS | T_A | MIN ⁽²⁾ | TYP ⁽³⁾ | MAX ⁽²⁾ | UNIT |
|--|-------------|---|---------------|--------------------|--------------------|--------------------|---------|
| Turn-On Time when Switching from One USB Path (or Disabled $\overline{OE}=1$) to Another USB Path | t_{ON} | $R_L = 50\Omega$, $C_L = 35pF$, $V_{SW} = 0.8V$, Figure 3, Figure 4 | $25^{\circ}C$ | | 200 | | μs |
| Turn-Off Time, Turning Off Any of the USB Paths | t_{OFF} | $R_L = 50\Omega$, $C_L = 35pF$, $V_{SW} = 0.8V$, Figure 3, Figure 4 | $25^{\circ}C$ | | 92 | | ns |
| Propagation Delay ⁽¹⁾ | t_{PD} | $C_L = 5pF$, $R_L = 50\Omega$, Figure 3, Figure 5 | $25^{\circ}C$ | | 0.35 | | ns |
| Slow Turn-On/Off Switch Paths ⁽¹⁾ | t_{RF} | $C_L = 5pF$, Dn at 0V or 3.6V, 40.5Ω in series with switch 10% to 90% | $25^{\circ}C$ | | 4.5 | | ns |
| Break-Before-Make Time | t_{BBM} | $R_L = 50\Omega$, $C_L = 35pF$, $V_{SW1}=V_{SW2}=0.8V$, Figure 7 | $25^{\circ}C$ | | 200 | | μs |
| -3dB Bandwidth | BW | $R_L = 50\Omega$, $C_L = 5pF$, Figure 8 | $25^{\circ}C$ | | 550 | | MHz |
| Off Isolation | O_{IRR} | $R_L = 50\Omega$, $f=240MHz$, Figure 9 | $25^{\circ}C$ | | -40 | | dB |
| Channel-to-Channel Crosstalk | X_{talk} | $R_L = 50\Omega$, $f=240MHz$, Figure 10 | $25^{\circ}C$ | | -40 | | dB |
| Pulse Skew ⁽¹⁾ | $t_{SK(P)}$ | $V_{SW} = 0.2V_{diffPP}$, $C_L = 5pF$, Figure 6 | $25^{\circ}C$ | | 25 | | ps |
| Skew Between Differential Signals Within a Pair ⁽¹⁾ | $t_{SK(I)}$ | $V_{SW} = 0.2V_{diffPP}$, $C_L = 5pF$, Figure 6 | $25^{\circ}C$ | | 25 | | ps |
| Input Capacitance | C_{IN} | $f=1MHz$, $V_{IN}=0$ to V_{CC} | $25^{\circ}C$ | | 3 | | pF |
| D+/D- On Capacitance | C_{ON} | $f=1MHz$, $V_{IN}=0$ to V_{CC} | $25^{\circ}C$ | | 11.5 | | pF |
| HSD0n, HSD1n, HSD2n, HSD3n Off Capacitance | C_{OFF} | $f=1MHz$, $V_{IN}=0$ to V_{CC} | $25^{\circ}C$ | | 2.8 | | pF |

(1) This parameter is ensured by design and/or characterization and is not tested in production.

(2) Limits are 100% production tested at $25^{\circ}C$. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

9 PARAMETER MEASUREMENT INFORMATION

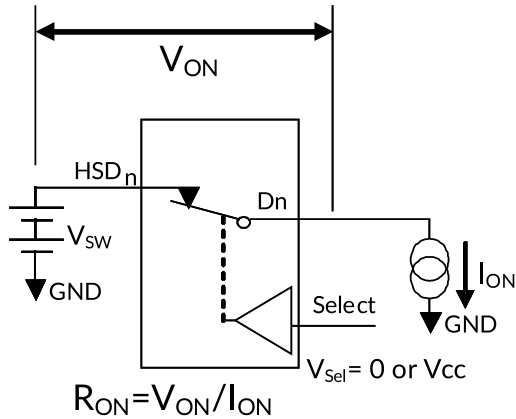
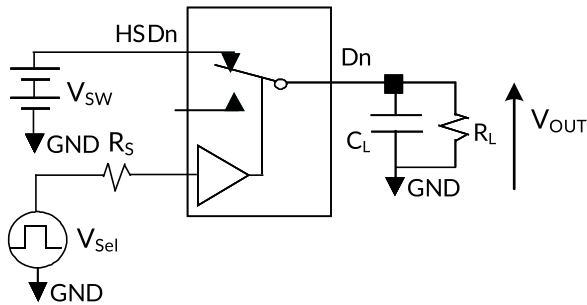
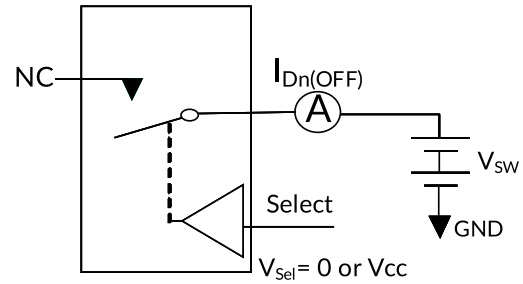


Figure 1. On Resistance



R_L , R_S and C_L are functions of the application environment (see AC Tables for specific values)
 C_L includes test fixture and stray capacitance.

Figure 3. AC Test Circuit Load



**Each switch port is tested separately

Figure 2. Off Leakage

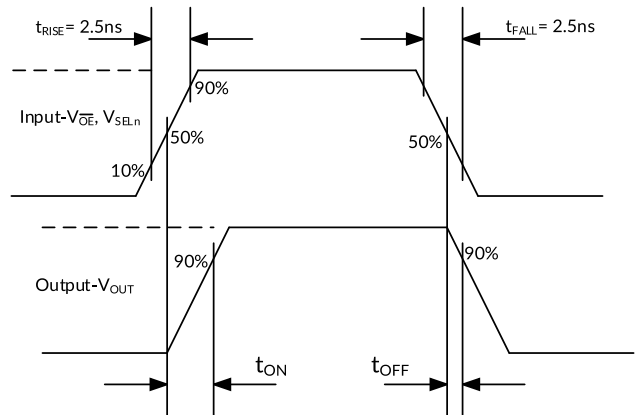


Figure 4. Turn-On / Turn-Off Waveforms

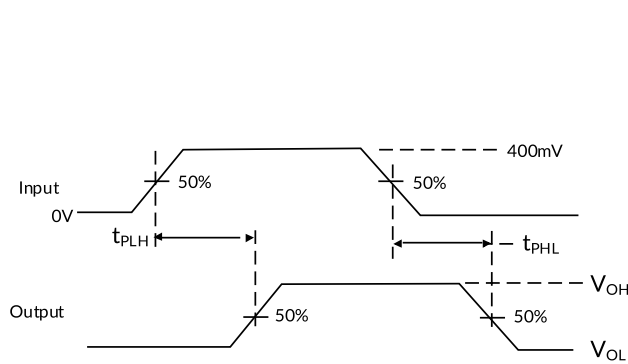


Figure 5. Propagation Delay (t_{rtF} - 500ps)

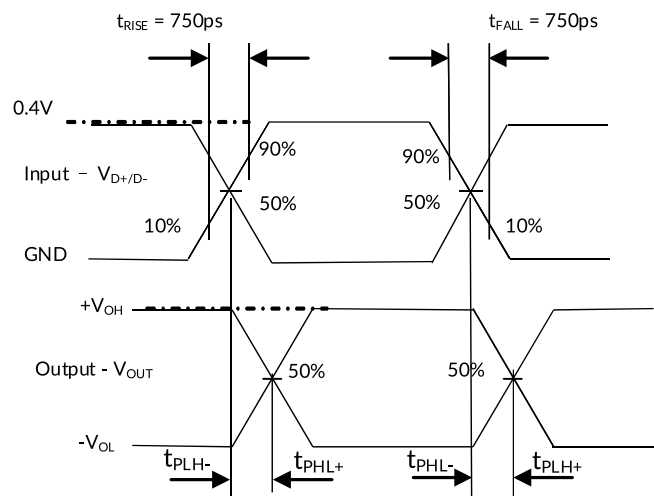


Figure 6. Skew Test Waveforms

$$t_{SK(P)} = |t_{PLH-} - t_{PHL-}| \text{ or } |t_{PLH+} - t_{PHL+}|$$

$$t_{SK(I)} = |t_{PLH-} - t_{PHL+}| \text{ or } |t_{PLH+} - t_{PHL-}|$$

PARAMETER MEASUREMENT INFORMATION (continued)

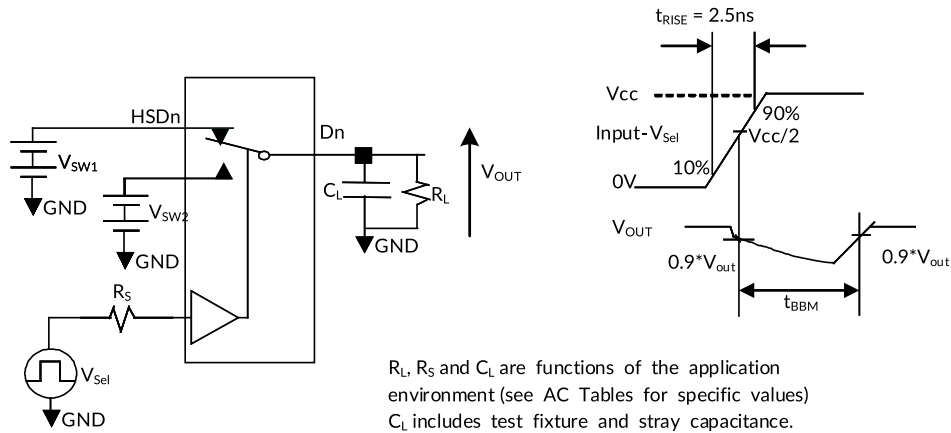


Figure 7. Break-Before-Make Interval Timing

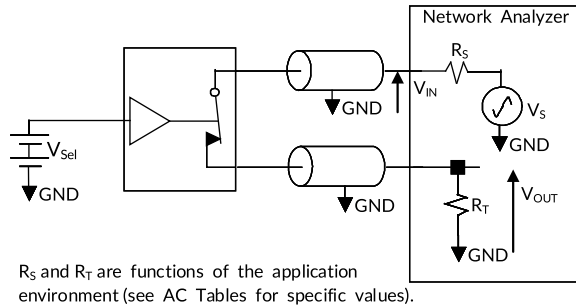


Figure 8. Bandwidth

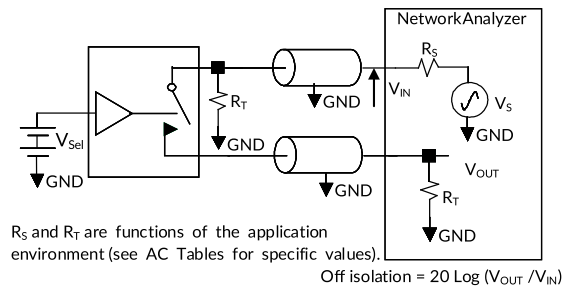


Figure 9. Channel Off Isolation

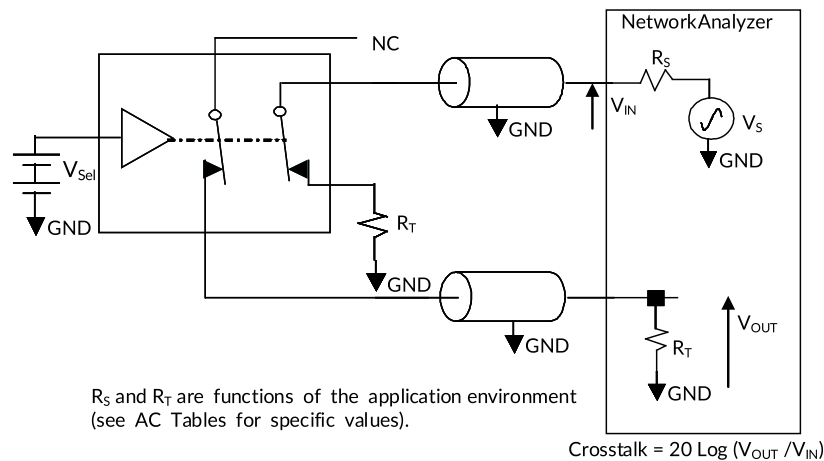


Figure 10. Non-Adjacent Channel-to-Channel Crosstalk

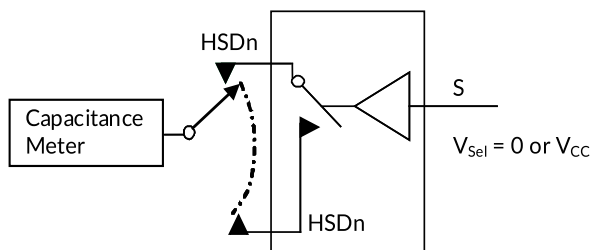


Figure 11. Channel Off Capacitance

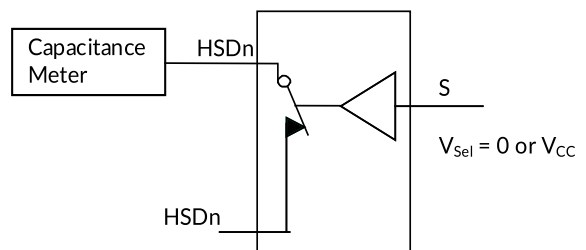


Figure 12. Channel On Capacitance

10 APPLICATION AND IMPLEMENTATION

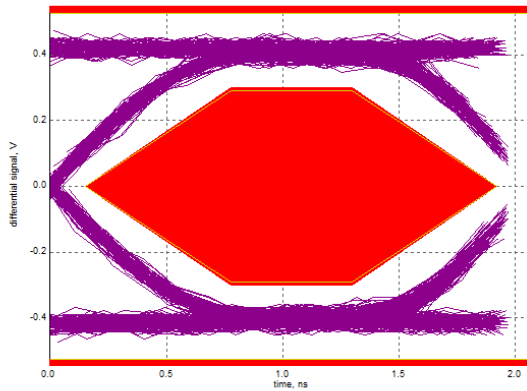


Figure 13. Eye Pattern:480-Mbps USB Signal with No Switch (Through Path)

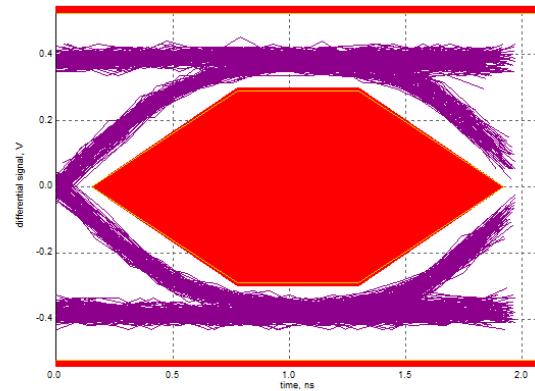


Figure 14. Eye Pattern:480-Mbps USB Signal with HSD0 Path

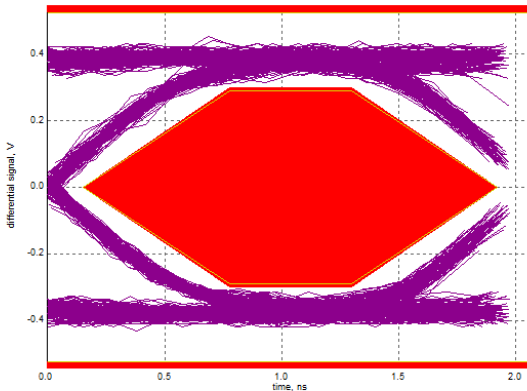


Figure 15. Eye Pattern:480-Mbps USB Signal with HSD1 Path

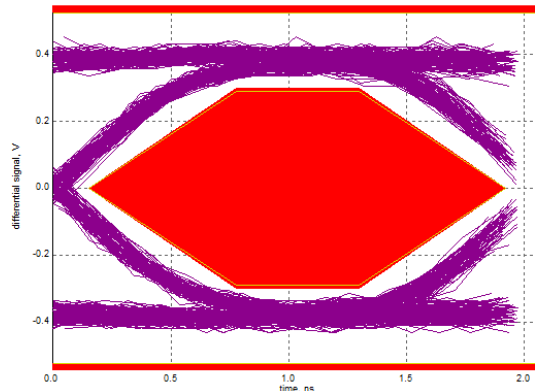


Figure 16. Eye Pattern:480-Mbps USB Signal with HSD2 Path

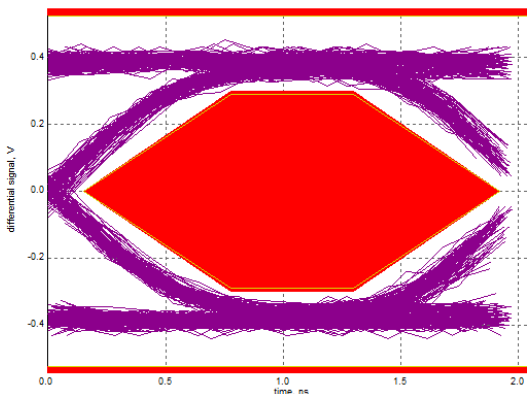
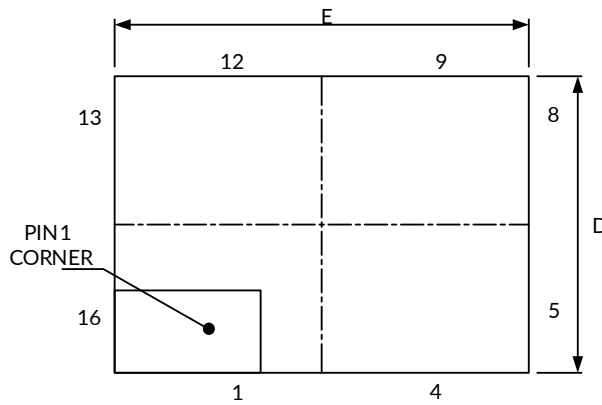


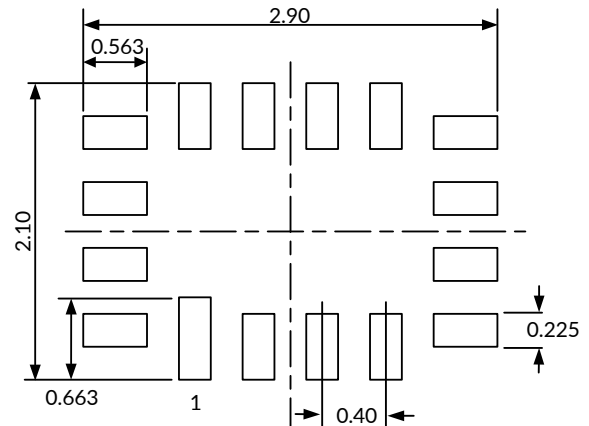
Figure 17. Eye Pattern:480-Mbps USB Signal with HSD3 Path

11 PACKAGE OUTLINE DIMENSIONS

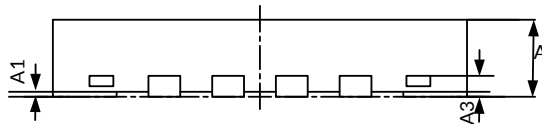
UQFN2.6X1.8-16 ⁽³⁾



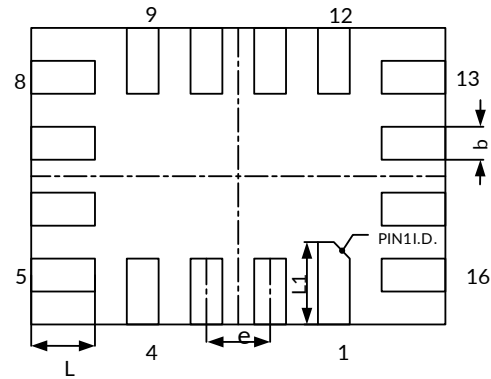
TOP VIEW



RECOMMENDED LAND PATTERN (Unit: mm)



SIDE VIEW



BOTTOM VIEW

| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|------------------|----------------------------|-------|----------------------------|-------|
| | Min | Max | Min | Max |
| A ⁽¹⁾ | 0.450 | 0.550 | 0.018 | 0.022 |
| A1 | 0.000 | 0.046 | 0.000 | 0.002 |
| A3 | 0.110 (REF) ⁽²⁾ | | 0.004 (REF) ⁽²⁾ | |
| b | 0.150 | 0.250 | 0.006 | 0.010 |
| E ⁽¹⁾ | 2.550 | 2.650 | 0.100 | 0.104 |
| D ⁽¹⁾ | 1.750 | 1.850 | 0.069 | 0.073 |
| e | 0.400 (TYP) | | 0.016 (TYP) | |
| L | 0.350 | 0.450 | 0.014 | 0.018 |
| L1 | 0.450 | 0.550 | 0.018 | 0.022 |

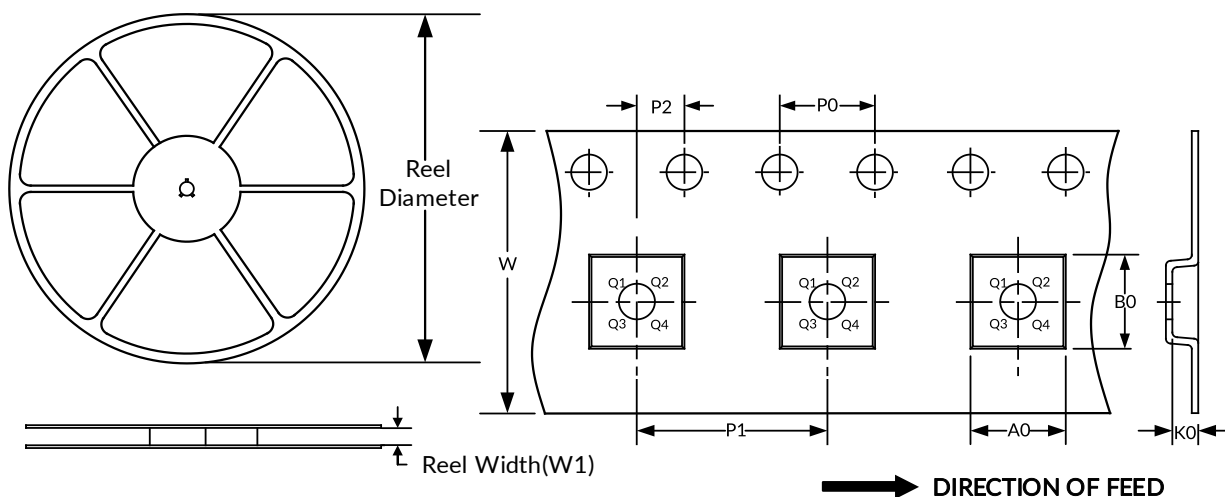
NOTE:

1. Plastic or metal protrusions of 0.075mm maximum per side are not included.
2. REF is the abbreviation for Reference.
3. This drawing is subject to change without notice.

12 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

| Package Type | Reel Diameter | Reel Width (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P0 (mm) | P1 (mm) | P2 (mm) | W (mm) | Pin1 Quadrant |
|----------------|---------------|-----------------|---------|---------|---------|---------|---------|---------|--------|---------------|
| UQFN2.6X1.8-16 | 7" | 8.3 | 2.10 | 2.90 | 0.75 | 4.0 | 4.0 | 2.0 | 8.0 | Q1 |

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

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